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Part Number: **0736441205**
Status: **Active**
Overview: HDM® Backplane Connector System
Description: HDM® Board-to-Board Backplane Header, Vertical, SMC, Press-Fit, Guide Post Location A, Polarizing Key Position C, 144 Circuits

Documents:

[3D Model](#) [RoHS Certificate of Compliance \(PDF\)](#)
[Drawing \(PDF\)](#)

Agency Certification

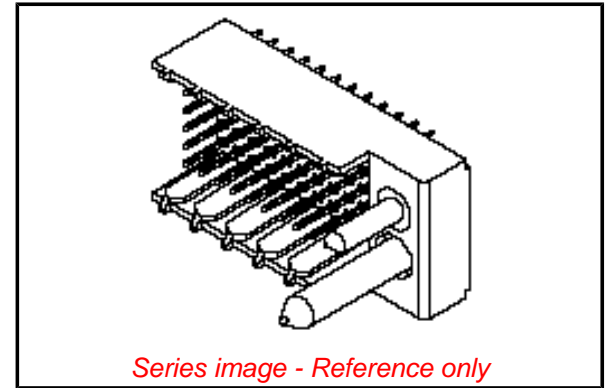
CSA LR19980
 UL E29179

General

Product Family Backplane Connectors
 Series 73644
 Application Backplane
 Comments Standard Press-Fit
 Component Type PCB Header
 Overview HDM® Backplane Connector System
 Product Name HDM®
 UPC 800754345279

Physical

Circuits (Loaded) 144
 Circuits (maximum) 144
 Color - Resin Black, Natural
 Durability (mating cycles max) 250
 First Mate / Last Break No
 Flammability 94V-0
 Guide to Mating Part Yes
 Keying to Mating Part Yes
 Material - Metal Phosphor Bronze, Stainless Steel
 Material - Plating Mating Gold
 Material - Plating Termination Gold
 Material - Resin High Temperature Thermoplastic
 Net Weight 9.729/g
 Number of Columns 24
 Number of Pairs Open Pin Field
 Number of Rows 6
 Orientation Vertical
 PC Tail Length 3.50mm
 PCB Locator No
 PCB Retention Yes
 PCB Thickness - Recommended 2.50mm
 Packaging Type Tube
 Pitch - Mating Interface 2.00mm
 Pitch - Termination Interface 2.00mm
 Plating min - Mating 0.762µm
 Plating min - Termination 0.051µm
 Polarized to PCB No
 Stackable Yes
 Surface Mount Compatible (SMC) Yes
 Temperature Range - Operating -55°C to +105°C
 Termination Interface: Style Through Hole - Compliant Pin



EU ELV

Not Relevant

EU RoHS

Compliant

REACH SVHC

Contains SVHC(2014 December 17): No

Halogen-Free

Status

Low-Halogen

Need more information on product environmental compliance?

Email productcompliance@molex.com
 Please visit the [Contact Us](#) section for any non-product compliance questions.

China ROHS

ELV

Green Image

Not Relevant

Search Parts in this Series

73644 Series

Mates With

73632 HDM PLUS® Board-to-Board Daughtercard Receptacle, 73780 HDM® Board-to-Board Daughtercard Receptacle

Application Tooling | FAQ

Tooling specifications and manuals are found by selecting the products below. Crimp Height Specifications are then contained in the Application Tooling Specification document.

Global

Description	Product #
Extraction Tool	<u>0621001000</u>
Backplane Insertion	<u>0621001400</u>
Signal Contact Tool	
Backplane Insertion	<u>0622005703</u>
Head for 144 Circuits	

Electrical

Current - Maximum per Contact	1.0A
Data Rate	1.0 Gbps
Real Signals (per 25mm)	75
Shielded	No
Voltage - Maximum	250V AC

Material Info**Reference - Drawing Numbers**

Sales Drawing	SDA-73644-****
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